

SN100C® LEAD-FREE SOLDER ALLOY

FEATURES

- Liquidus 227°C (441°F)
- Smooth, Bright Solder Joints
- Bridge-Free Soldering
- Low Cost - Does Not Contain Silver
- Reduced Copper Erosion from Holes, Pads and Tacks
- Dross Rate Similar to Tin-Lead Alloys
- Complies with IPC J-STD-006

DESCRIPTION

SN100C is a lead-free silver-free solder alloy developed by Nihon Superior in Japan. SN100C offers user-friendly properties and has been proven in commercial applications since 1999. The inclusion of nickel reduces copper dissolution and produces a bright shiny solder fillet. The addition of germanium reduces dross formation and promotes solder flow. Performance in wave and selective soldering is similar to SAC alloys at considerably lower cost. SN100C is available in bar, solid and cored wire, and solder paste.

AVAILABILITY

SN100C is available in 1.1 kg (2.5 lb) triangular bars, 3 kg AIM Safety Bar and Solid Wire. SN100C is also available in AIM flux cored wire solder and solder paste.

TYPICAL ALLOY COMPOSITION

Typical Alloy Composition			
Sn: Balance	Cu: 0.7	Ni: 0.05	Ge: 0.009

TYPICAL MELTING TEMPERATURE

Typical Melting Temperature
227°C (441°F) Eutectic

TYPICAL SPECIFIC GRAVITY

Alloy Density
7.4 g/cm ³ (Archimedes method)



HANDLING & STORAGE

Parameter	Time	Temperature
Shelf Life	Indefinite	Room Temperature

Indefinite shelf life applies to solid solder. For other product categories, refer to those specific TDSs. Consult AIM SN100C SDS for additional handling procedures and precautions.

FLUX COMPATIBILITY

SN100C bar solder is compatible with all no-clean and water soluble electronic grade fluxes.

CLEANING

Refer to data sheets provided by the flux manufacturer.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.